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### MMBD4148TW / BAS16TW

#### SURFACE MOUNT FAST SWITCHING DIODE ARRAY

#### **Features**

- · Fast Switching Speed
- Ultra-Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

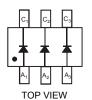
### **Mechanical Data**

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 @3
- · Polarity: See Diagram
- Weight: 0.006 grams (approximate)

**SOT363** 







Internal Schematic

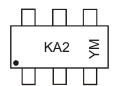
### Ordering Information (Note 4)

Part Number	Case	Packaging
MMBD4148TW-7-F	SOT363	3000/Tape & Reel
BAS16TW-7-F	SOT363	3000/Tape & Reel
BAS16TW-13-F	SOT363	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# Marking Information



KA2 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: B = 2014) M = Month (ex: 9 = September)

#### Date Code Key

Year	2000	2001	2002		2010	2011	2012	2013	2014	4 2015	2016	2017	2018
Code	L	М	N		Х	Υ	Z	Α	В	С	D	Е	F
Month	Jan	Feb	Mar	Apr	Ma	y Ju	ın ,	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	(	3	7	8	9	0	N	D



### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage		$V_{RM}$	100	V
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	75	٧
RMS Reverse Voltage		$V_{R(RMS)}$	53	V
Forward Continuous Current 51)	(Note	I <sub>FM</sub>	300	mA
Average Rectified Output Current 51)	(Note	Io	150	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0µs @ t = 1.0s	I <sub>FSM</sub>	2.0 1.0	А

### **Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 5)	$P_{D}$	200	mW
Thermal Resistance Junction to Ambient Air	(Note 5)	$R_{ hetaJA}$	625	°C/W
Operating and Storage Temperature Range		$T_J,T_STG$	-65 to +150	°C

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

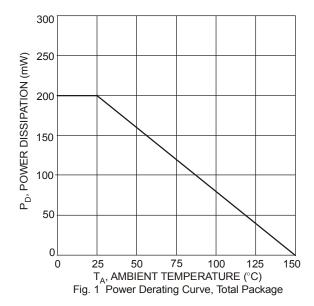
Characteristic		Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage	(Note 6)	$V_{(BR)R}$	75	_	V	$I_R = 1\mu A$
Forward Voltage		V <sub>F</sub>	_	0.715 0.855 1.0 1.25	<b>V</b>	I <sub>F</sub> = 1.0mA I <sub>F</sub> = 10mA I <sub>F</sub> = 50mA I <sub>F</sub> = 150mA
Reverse Current	(Note 6)	I <sub>R</sub>	_	1.0 50 30 25	μΑ μΑ μΑ nA	$V_R = 75V$ $V_R = 75V$ , $T_J = +150$ °C $V_R = 25V$ , $T_J = +150$ °C $V_R = 20V$
Total Capacitance		C <sub>T</sub>	_	2.0	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time		t <sub>rr</sub>	_	4.0	ns	$I_F = I_R = 10 \text{mA},$ $I_{rr} = 0.1 \text{ x } I_R, R_L = 100 \Omega$

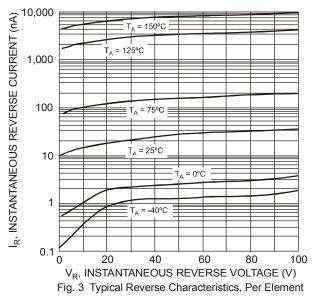
Notes:

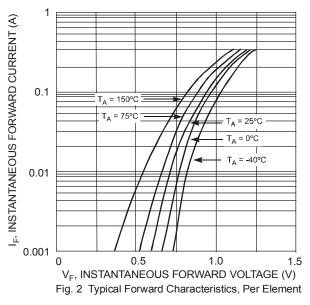
<sup>5.</sup> Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

<sup>6.</sup> Short duration pulse test used to minimize self-heating effect.









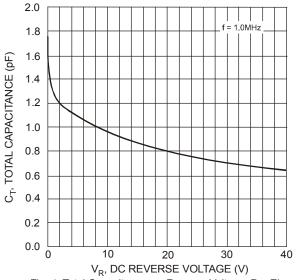
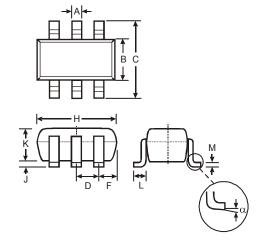


Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

## **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

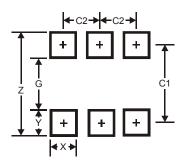


Dim A B C	0.10 1.15 2.00	0.30 1.35 2.20	7yp 0.25 1.30 2.10				
В	1.15	1.35	1.30				
	2.00	2.20					
С			2.10				
D	0.65 Typ						
F	0.40	0.45	0.425				
Н	1.80	2.20	2.15				
J	0	0.10	0.05				
K	0.90	1.00	1.00				
L	0.25	0.40	0.30				
M	0.10	0.22	0.11				
α	0°	8°	-				
All Dimensions in mm							



### Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Υ	0.6
C1	1.9
C2	0.65

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